iC-LFS
32x1 LINEAR IMAGE SENSOR

FEATURES

♦ 32 active photo pixels of 56 µm at a pitch of 63.5 µm (400 DPI)
♦ Integrating L-V conversion followed by a sample & hold circuit
♦ High sensitivity and uniformity over wavelength
♦ High clock rates of up to 5 MHz
♦ Only 32 clocks required for readout
♦ Shutter function enables flexible integration times
♦ Glitch-free analogue output
♦ Push-pull output amplifier
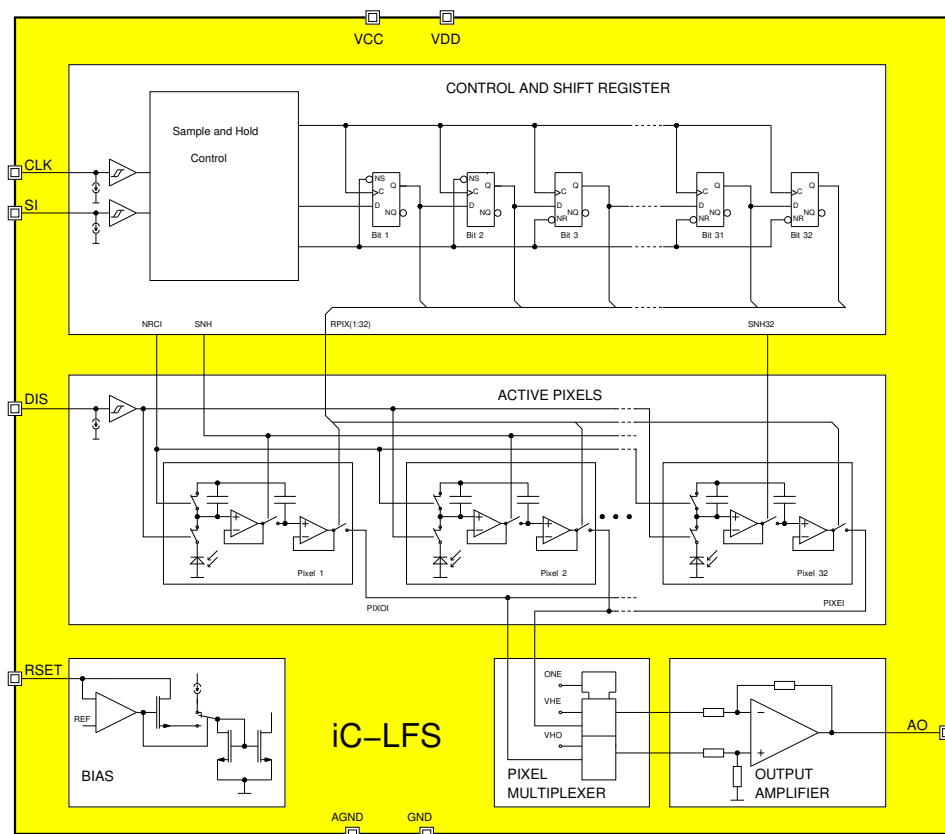♦ 5 V single supply operation

APPLICATIONS

♦ Optical line sensors
♦ CCD substitute

PACKAGES
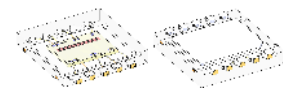
cDFN10 4 mm x 4 mm

BLOCK DIAGRAM

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DESCRIPTION

iC-LFS is an integrating light-to-voltage converter with a single line of 32 pixels pitched at 63.5 µm (center-to-center distance). Each pixel consists of a 56.4 µm x 200 µm photodiode, an integration capacitor and a sample and hold circuit.

The integrated control logic makes operation very simple, with only a start and clock signal necessary. A third control input enables the integration period to be paused at any time (electronic shutter).

With the start signal the hold mode is activated for all pixels simultaneously with the next rising clock edge; starting with pixel 1 the hold voltages are switched in sequence to the push-pull output amplifier. The second clock pulse deletes all integration capacitors and the integration period starts again in the background during the output phase. A run is complete after 32 clock pulses.

iC-LFS is suitable for high clock rates of up to 5 MHz. If this is not required the supply current can be reduced via the external bias setting.

PACKAGING INFORMATION cDFN10 4 mm x 4 mm

PIN CONFIGURATION cDFN10 4 mm x 4 mm
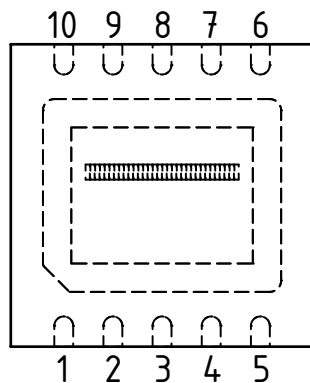

PIN FUNCTIONS

No.	Name	Function
1	SI	Start Integration Input
2	CLK	Clock Input
3	AO	Analogue Output
4	VDD	+5 V Digital Supply Voltage
5	VCC	+5 V Analogue Supply Voltage
6	RSET	Bias Current (resistor from VCC to RSET; when connected to GND the internal bias setting is activated)
7	n.c.	
8	AGND	Analogue Ground
9	GND	Digital Ground
10	DIS	Shutter control

The *E-Pad* is to be connected to a Ground Plane (AGND) on the PCB.

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PACKAGE DIMENSIONS cDFN-4x4

All dimensions given in mm.

RECOMMENDED PCB-FOOTPRINT

SIDE

TOP

BOTTOM
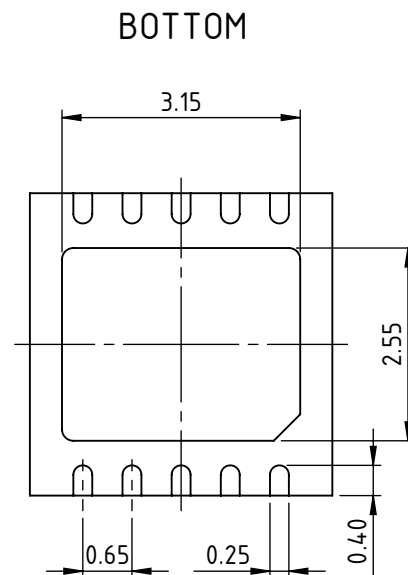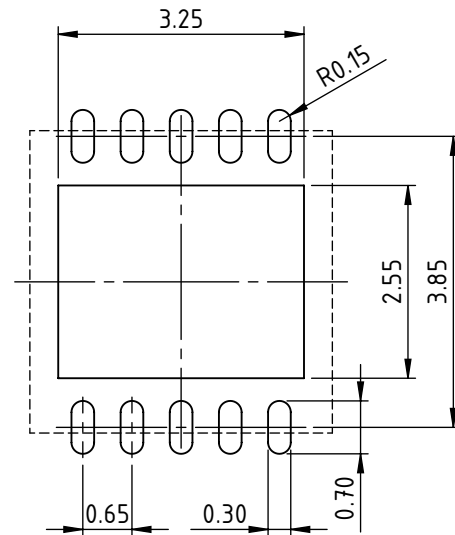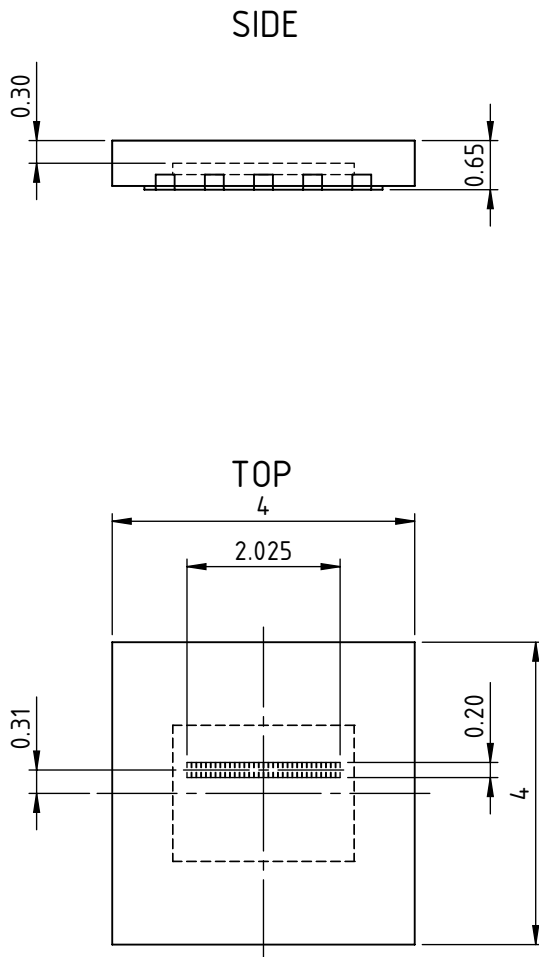
All dimensions given in mm. Tolerances of form and position according to JEDEC MO-229.
Tolerance of sensor pattern: ±0.10mm / ±1° (with respect to center of backside pad).

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ABSOLUTE MAXIMUM RATINGS

Beyond these values damage may occur; device operation is not guaranteed.

Item No.	Symbol	Parameter	Conditions	Min.	Max.	Unit
G001	VDD	Digital Supply Voltage		-0.3	6	V
G002	VCC	Analogue Supply Voltage		-0.3	6	V
G003	V()	Voltage at SI, CLK, DIS, RSET, AO		-0.3	VCC + 0.3	V
G004	I()	Current in RSET, AO		-10	10	mA
G005	Vd()	ESD Susceptibility at all pins	HBM, 100 pF discharged over 1.5 kΩ		4	kV
G006	Tj	Operating Junction Temperature		-40	125	°C

THERMAL DATA

Operating Conditions: VCC = VDD = 5 V ±10%

Item No.	Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
T01	Ta	Operating Ambient Temperature Range		0		70	°C

All voltages are referenced to ground unless otherwise stated.
All currents flowing into the device pins are positive; all currents flowing out of the device pins are negative.

ELECTRICAL CHARACTERISTICS

Operating Conditions: VCC = VDD = 5 V ±10%, RSET = GND, Tj = -25...85 °C unless otherwise noted

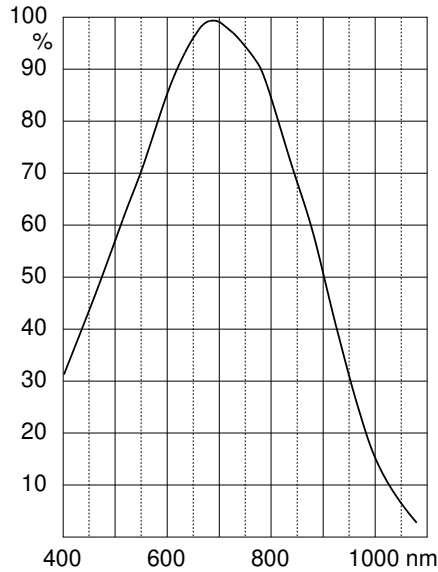| Item No.	Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Total Device							
001	VDD	Digital Supply Voltage Range		4.5		5.5	V
002	VCC	Analogue Supply Voltage Range		4.5		5.5	V
003	I(VDD)	Supply Current in VDD	f(CLK) = 1 MHz f(CLK) = 5 MHz		70		μA
004	I(VCC)	Supply Current in VCC			4.5	7	mA
005	Vc()hi	Clamp Voltage hi at SI, CLK, DIS, RSET	Vc()hi = V() $-$ VCC; I() = 1 mA	0.3		1.8	V
006	Vc()lo	Clamp Voltage lo at SI, CLK, DIS, RSET	Vc()hi = V() $-$ V(AGND); I() = -1 mA	-1.5		-0.3	V
007	Vc()hi	Clamp Voltage hi at AO	Vc()hi = V(AO) $-$ VCC; I(AO) = 1 mA	0.3		1.5	V
008	Vc()lo	Clamp Voltage lo at AO, VCC, VDD, GND	Vc()lo = V() $-$ V(AGND); I() = -1 mA	-1.5		-0.3	V
Photodiode Array							
201	A()	Radiant Sensitive Area	200 μm x 56.40 μm per Pixel		0.01128		mm^2
202	S(λ)max	Spectral Sensitivity	λ = 680 nm (see Fig. 1)		0.5		A/W
203	λ_{ar}	Spectral Application Range	S(λ_{ar}) = 0.25 x S(λ)max (see Fig. 1)	400		980	nm
Analogue Output AO							
301	Vs()lo	Saturation Voltage lo	I() = 1 mA			0.5	V
302	Vs()hi	Saturation Voltage hi	Vs()hi = VCC $-$ V(), I() = -1 mA			1	V
303	K	Sensitivity	λ = 680 nm		2.88		V/pWs
304	V0()	Offset Voltage	integration time 1 ms, no illumination		400	800	mV
305	ΔV0()	Offset Voltage Deviation during integration mode	ΔV0() = V(AO)t1 $-$ V(AO)t2, Δt = t2 $-$ t1 = 1 ms	-250		50	mV
306	ΔV()	Signal Deviation during hold mode	ΔV0() = V(AO)t1 $-$ V(AO)t2, Δt = t2 $-$ t1 = 1 ms	-150		150	mV
307	tp(CLK-AO)	Settling Time	Cl(AO) = 10 pF, CLK lo $\rightarrow$ hi until V(AO) = 0.98 x V(VCC)			200	ns
Power-On-Reset							
801	VCCon	Power-On Release by VCC				4.4	V
802	VCCoff	Power-Down Reset by VCC		1			V
803	VCChys	Hysteresis	VCChys = VCCon $-$ VCCoff	0.4	1	2	V
Bias Current Adjust RSET							
901	Ibias()	Permissible External Bias Current		20		100	μA
902	Vref	Reference Voltage	I(RSET) = Ibias	2.5	3	3.5	V
Input Interface SI, CLK, DIS							
B01	Vt()hi	Threshold Voltage hi		1.4		1.8	V
B02	Vt()lo	Threshold Voltage lo		0.9		1.2	V
B03	Vt()hys	Hysteresis	Vt()hys = Vt()hi $-$ Vt()lo	300		800	mV
B04	I()	Pull-Down Current		10	30	50	μA
B05	fclk	Permissible Clock Frequency				5	MHz

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OPTICAL CHARACTERISTICS: Diagrams

Figure 1: Relative spectral sensitivity

OPERATING REQUIREMENTS: Logic

Operating Conditions: VCC = VDD = 5 V ±10%, Tj = -25...85 °C
input levels lo = 0...0.45 V, hi = 2.4 V...VCC, see Fig. 2 for reference levels

Item No.	Symbol	Parameter	Conditions	Min.	Max.	Unit
I001	tset	Setup Time: SI stable before CLK lo → hi	see Fig. 3	50		ns
I002	thold	Hold Time: SI stable after CLK lo → hi	see Fig. 3	50		ns
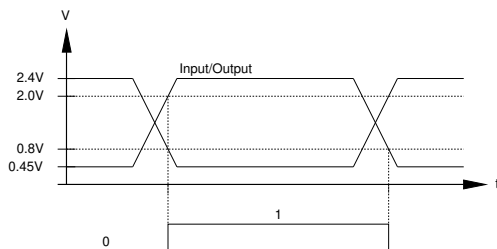
Figure 2: Reference levels
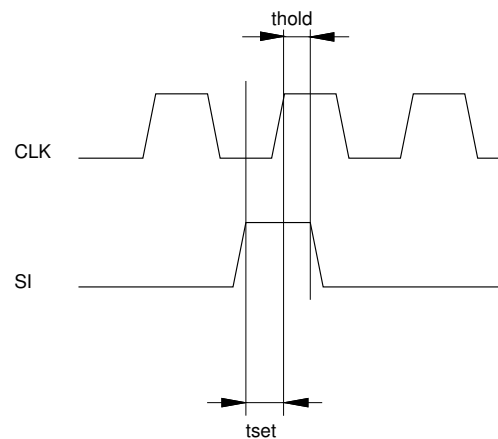
Figure 3: Timing diagram

DESCRIPTION OF FUNCTIONS

Normal operation

Following an internal power-on reset the integration and hold capacitors are discharged and the sample and hold circuit is set to sample mode. A high signal at SI and a rising edge at CLK triggers a readout cycle and with it a new integration cycle.

In this process the hold capacitors of pixels 1 to 31 are switched to hold mode immediately (SNH = 1), with pixel 32 (SNH32 = 1) following suit one clock pulse later. This special procedure allows all pixels to be read out with just 32 clock pulses. The integration capacitors are discharged by a one clock long reset signal (NRCI = 0) which occurs between the 2nd and 3rd falling edge of the readout clock pulse (cf. Figure 4). After the 31 pixels have been read out these are again set to sample mode (SNH = 0), likewise for pixel 32 one clock pulse later (SNH32 = 0).
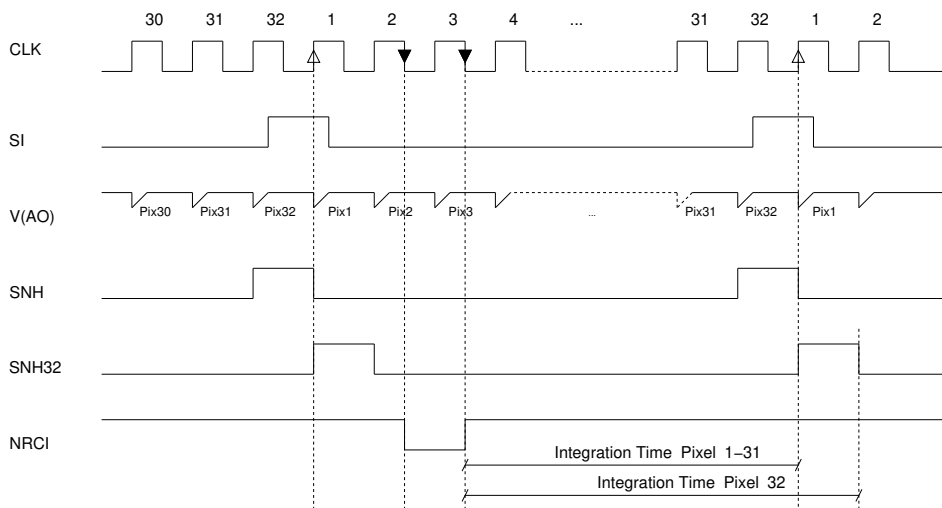
Figure 4: Readout cycle and integration sequence

If prior to the 32th clock pulse a high signal occurs at SI the present readout is halted and immediately reinitiated with pixel 1. In this instance the hold capacitors retain their old value i.e. hold mode prevails (SNH/SNH32 = 0).
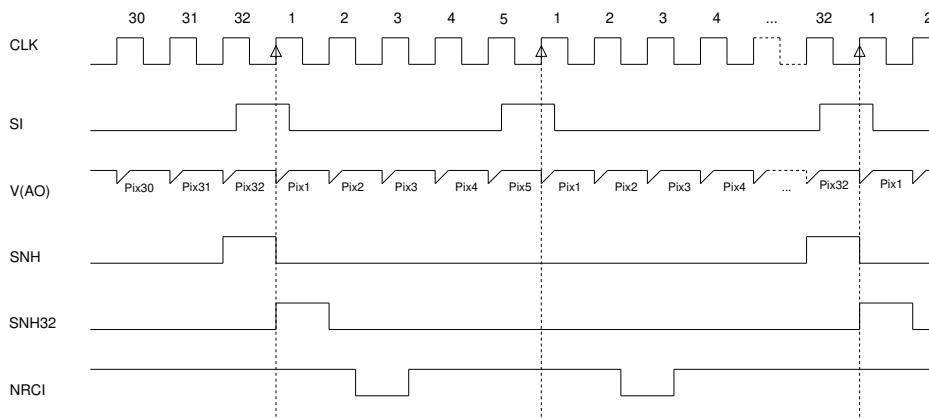
Figure 5: Restarting a readout cycle

With more than 32 clock pulses until the next SI signal, pixel 1 is output without entering hold mode; the output voltage tracks the voltage of the pixel 1 integration capacitor.
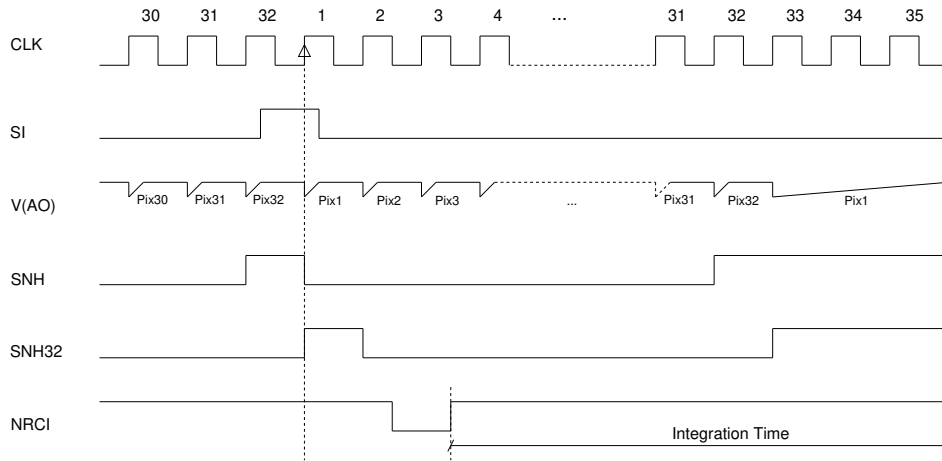
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Figure 6: Clock pulse continued without giving a new integration start signal

Operation with the shutter function

Integration can be halted at any time via pin DIS, i.e. the photodiodes are disconnected from their corresponding integration capacitor when DIS is high and the current integration capacitor voltages are maintained. If this pin is open or switched to GND the pixel photocurrents are summed up by the integration capacitors until the next successive SI signal follows.
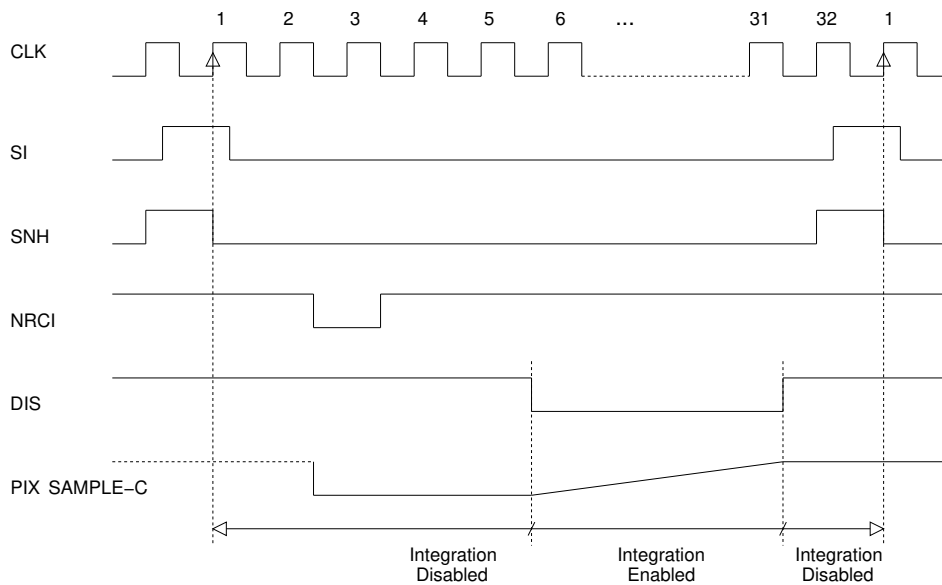
Figure 7: Defining the integration time via shutter input DIS

External bias current setting

In order to reduce the power consumption of the device an external reference current can be supplied to pin RSET which reduces the maximum readout frequency, however. To this end a resistor must be connected from VCC to RSET. If this pin is not used, it should be connected to GND.

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REVISION HISTORY

Rel.	Rel. Date*	Chapter	Modification	Page
A2	2015-10-20	PACKAGES	Image updated	1
		PACKAGING INFORMATION	Pin-out image updated Dimensions updated to final height	2 3
		ELECTRICAL CHARACTERISTICS	003: Value edded 004: Values added 006: Leading sign of Max. value corrected	5

* Release Date format: *YYYY-MM-DD*

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ORDERING INFORMATION

Type	Package	Order Designation
iC-LFS	clearDFN10 4 mm x 4 mm	iC-LFS cDFN10

Please send your purchase orders to our order handling team:

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E-Mail: dispo@ichaus.com

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